IPC ASSOCIATION ELECTRONICS	Material Comp © Copyright 2005. International and Pa	position Dec IPC, Bannockb n-American co	claration ourn, Illinois. A opyright conve	all rights reserved unontions.	der both	This docume level parts, the	ent is a declaration	ation of the encompa	ne substances asses all lowe	within the manufacturer level materials for v	rer listed which the i	item. Note nanufactu	e: if the item is an as arer has engineering	sembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and M	ials and Mfg Information				
Supplier	Information														
Company n	ame*	Company un	Company unique ID			Unique ID Authority					Response Date*				
nsemi											2023-00	2023-06-08			
Contact Na	me	Title - Contact			I	Phone - Contact*				Email -	Email - Contact*				
Product-Er	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-E1	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Dat	te Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
	AMIS30624C6244G I2C 800MA S		I2C 800MA STEPF	EPPER DRIVER		2023-06-08		:	PHG		612.57	mg	Each		
Manufact	turing Proccess Informa	ntion						<u> </u>					,	,	
7	Terminal Plating / Grid Array Material Te			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Tempera		ly Temperatu	ture Max Time at Peak Temper		ture Nu	mber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Al			U Alloy 2				260 C 30		seconds 3						
Comments															
TTENTIC	ON: MSL 2 Rated item require	es Dry Pack (a	fter electrical	test)											
or more in	formation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a							
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight 35.93	Unit of Measure
Die	35.93	mg	Supplier	Silicon (Si)	7440-21-3			
Die Attach	6.55	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		1.5065	mg
			Supplier	Silver (Ag)	7440-22-4		5.0435	mg
Lead Frame	188.57	mg	Supplier	Zinc (Zn)	7440-66-6		0.1886	mg
			Supplier	Iron (Fe)	7439-89-6		4.3371	mg
			Supplier	Copper (Cu)	7440-50-8		183.8558	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1886	mg
Mold Compound-Black	377.0	mg		Epoxy Phenol Resin	proprietary data		39.585	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		337.415	mg
Plating	3.7	mg	Supplier	Tin (Sn)	7440-31-5		3.7	mg
Wire Bond - Au	0.82	mg	Supplier	Gold (Au)	7440-57-5		0.82	mg